



Power MOSFETS

DATASHEET

LM80034N HK8A

N-Channel
Enhancement Mode MOSFET



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Quality Management Systems

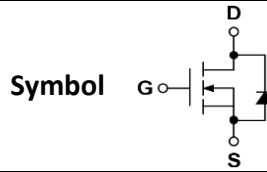
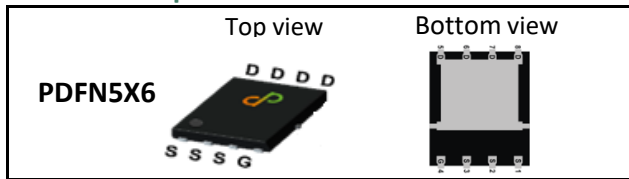
ISO 9001:2015 Certificate

LM80034NHK8A



N-Channel Enhancement Mode MOSFET

Pin Description



Product Summary

Symbol	N-CH	Unit
V_{DSS}	80	V
$R_{DSON (MAX)}$	3.7	mΩ
I_D	141.6	A

Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested
- ESD Level > 2kV

Applications

- DC-to-DC converters

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM80034NHK8A	PDFN5X6	Tape & Reel	5000 / Tape & Reel	80034 □□□□□□

Note : □□□□□□ = Lot Code

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

SYMBOL	PARAMETERS	Test Condition	MIN	TYP	MAX	UNIT
V_{DSS}	Drain-Source Voltage		80	-	-	V
V_{GSS}	Gate-Source Voltage		-20	-	20	V
T_j	Maximum Junction Temperature		-55	-	175	$^\circ\text{C}$
T_{stg}	Storage Temperature Range		-55	-	175	$^\circ\text{C}$
I_{SP}	Diode Pulse Current ¹	$T_C = 25^\circ\text{C}$	-	-	95	A
I_S	Diode Continuous Forward Current	$T_C = 25^\circ\text{C}$	-	-	38	A
I_{DM}	Pulsed Drain Current ¹	$T_C = 25^\circ\text{C}$	-	-	566	A
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-	-	141.6	A
		$T_C = 100^\circ\text{C}$	-	-	102	
P_D	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	-	-	150	W
		$T_C = 100^\circ\text{C}$	-	-	75	
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	-	-	21	A
		$T_A = 70^\circ\text{C}$	-	-	17	
P_D	Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	-	-	3.1	W
		$T_A = 70^\circ\text{C}$	-	-	2.2	
I_{AS}	Avalanche Current, Single pulse ²	$L = 0.1\text{mH}$	-	-	55	A
E_{AS}	Avalanche Energy, Single pulse ²	$L = 0.1\text{mH}$	-	-	140	mJ
E_{AR}	Avalanche energy, repetitive ²	$L = 0.1\text{mH}$	-	-	0.7	mJ
dv/dt	MOSFET dv/dt ruggedness	$V_{DS}=0\dots 40\text{V}$	-	-	10	V/ns
dv/dt	Reverse diode dv/dt	$I_F=10\text{A}, V_R=64\text{V}$	-	-	10	V/ns
diF/dt	Maximum diode commutation speed	$I_F=10\text{A}, V_R=64\text{V}$	-	-	100	A/us

Note ① : Max. current is limited by junction temperature

Note ② : UIS tested and pulse width are limited by maximum junction temperature 175 $^\circ\text{C}$

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Thermal Characteristics

SYMBOL	PARAMETERS	Rating	UNIT
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	1 °C / W
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient ³	Steady State	48 °C / W

N-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	80	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	3.0	4.0	V
I_{GSS}	Gate-Body Leakage	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
$R_{DS(ON)}$	Drain-Source On-State Resistance ⁴	$V_{GS} = 10V, I_D = 20A$	1.5	3.1	3.7	m Ω
g_{fs}	Forward Transconductance	$V_{DS} = 5V, I_D = 10A$	-	32	-	S
Dynamic Characteristics (5)						
R_g	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f = 1MHz$	0.1	0.8	1.6	Ω
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 40V, f = 1MHz$	1968	3935	5903	pF
C_{oss}	Output Capacitance		580	1160	2320	
C_{rss}	Reverse Transfer Capacitance		51	101	202	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 40V, V_{GS} = 10V, I_D = 1A, R_{GEN} = 1\Omega$	-	19.3	-	nS
t_r	Turn-On Rise Time		-	12.3	-	
$t_{d(off)}$	Turn-Off Delay Time		-	47.5	-	
t_f	Turn-Off Fall Time		-	92.8	-	
$Q_g(V_{GS}=6V)$	Total Gate Charge	$V_{DS} = 40V, V_{GS} = 10V, I_D = 20A$	27	53.5	80	nC
$Q_g(V_{GS}=10V)$	Total Gate Charge		42	84.2	126	
Q_{gs}	Gate-Source Charge		13	26.5	40	
Q_{gd}	Gate-Drain Charge		8.0	16	24	
Source-Drain Characteristics						
V_{SD}	Diode Forward Voltage ⁴	$I_{SD} = 10A, V_{GS} = 0V$	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	$I_F=10A, V_R=64V, di_F/dt=100A/\mu s$	-	60.5	121	nS
Q_{rr}	Reverse Recovery Charge		-	86	172	nC
I_{rm}	Peak reverse recovery current		-	2.3	3.4	A

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz

Note ④ : Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

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N-Channel Typical Characteristics

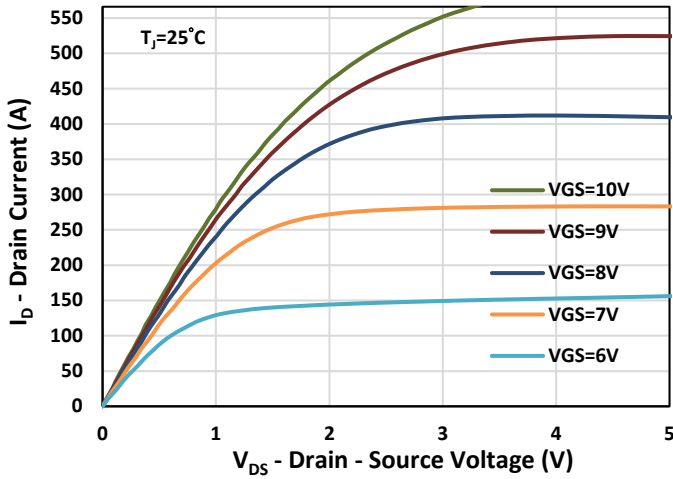


Fig.1 Output Characteristics

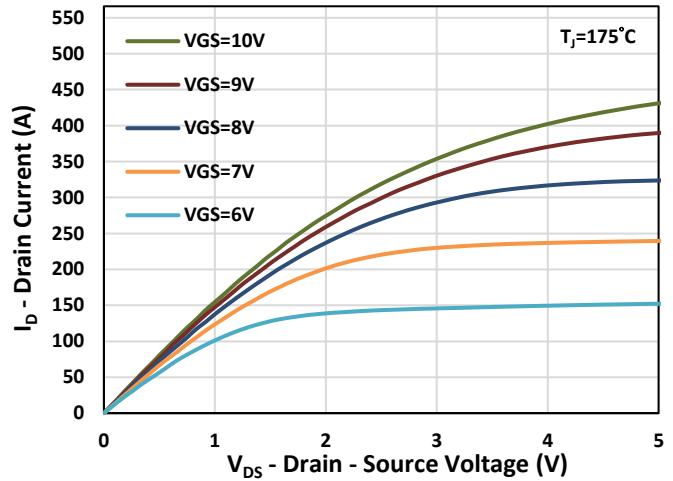


Fig.2 Output Characteristics

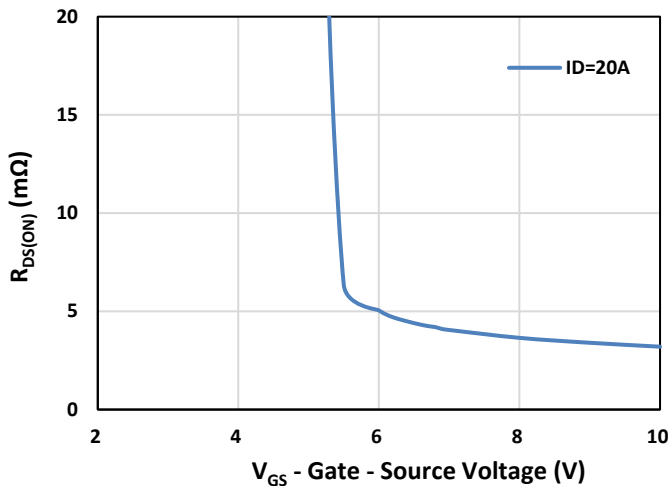


Fig.3 On-Resistance vs. V_{GS}

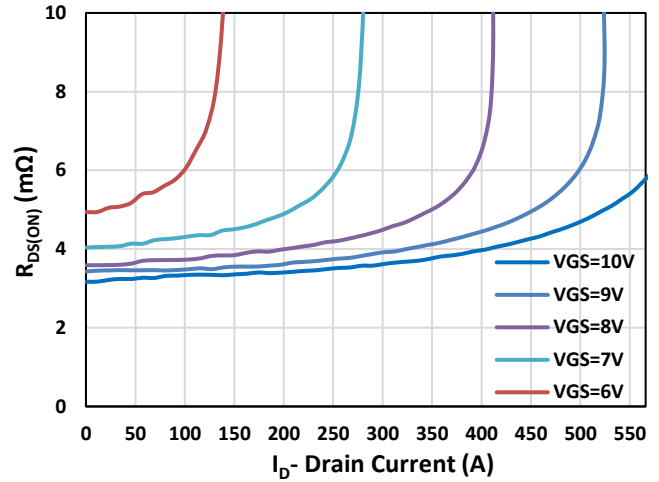


Fig.4 On-Resistance vs. I_D

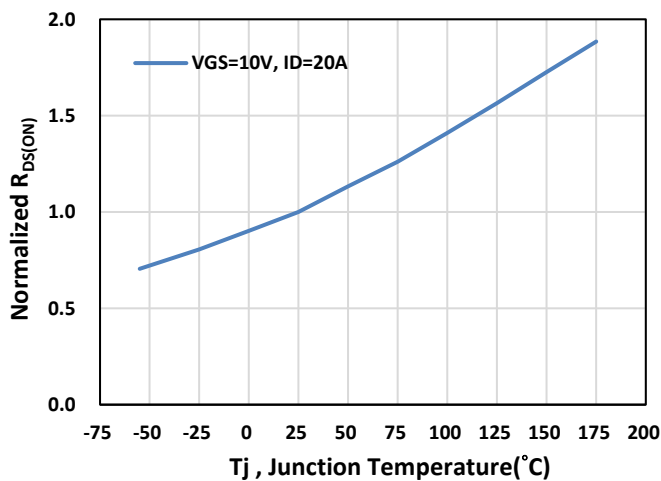


Fig.5 Drain-Source On Resistance

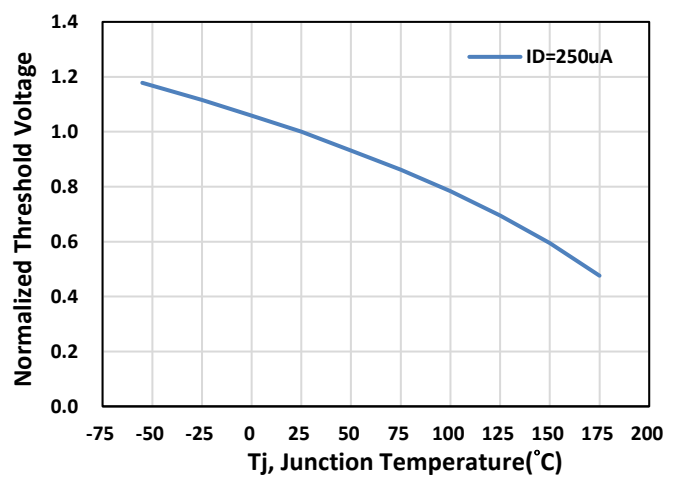


Fig.6 Gate Threshold Voltage

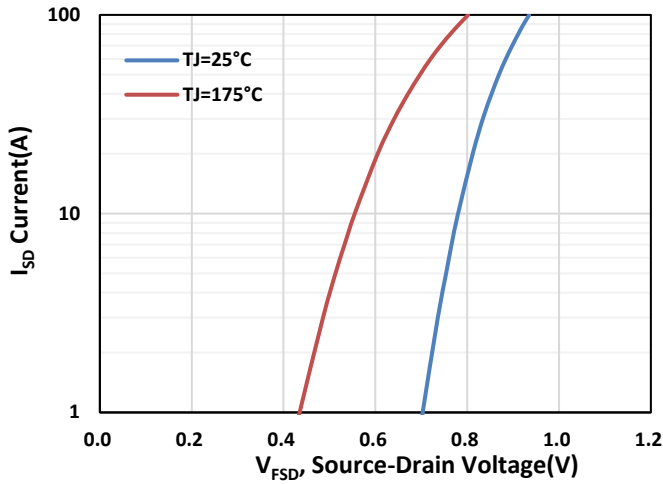


Fig.7 Source-Drain Diode Forward

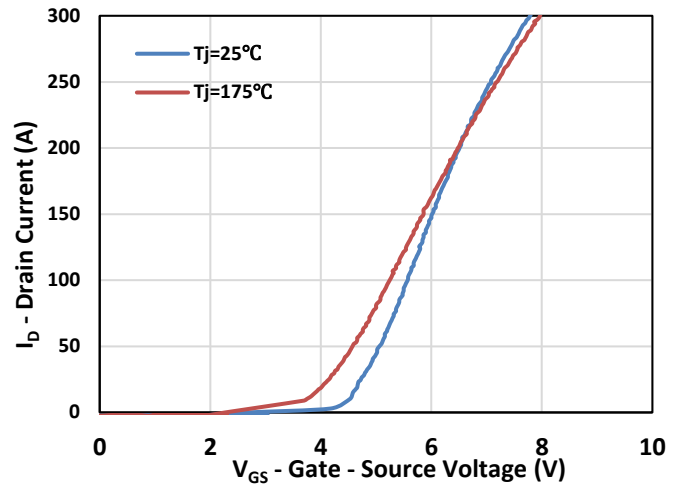


Fig.8 Transfer Characteristics

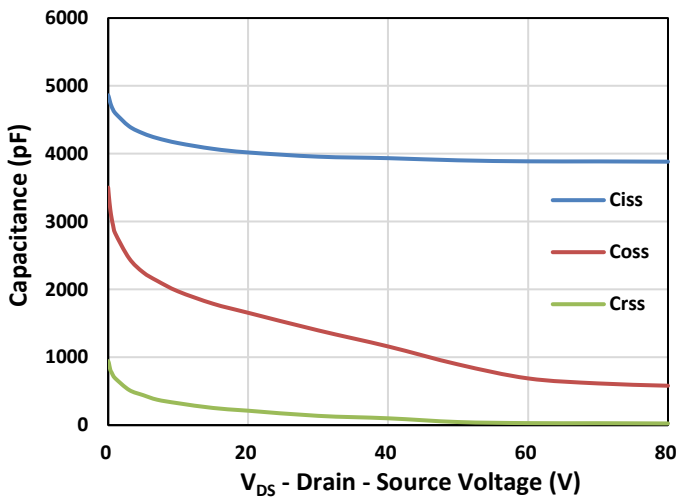


Fig.9 Capacitance

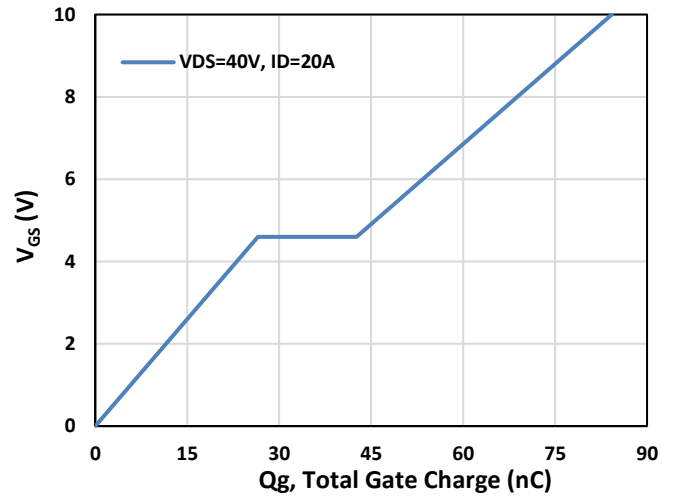


Fig.10 Gate Charge Characteristics

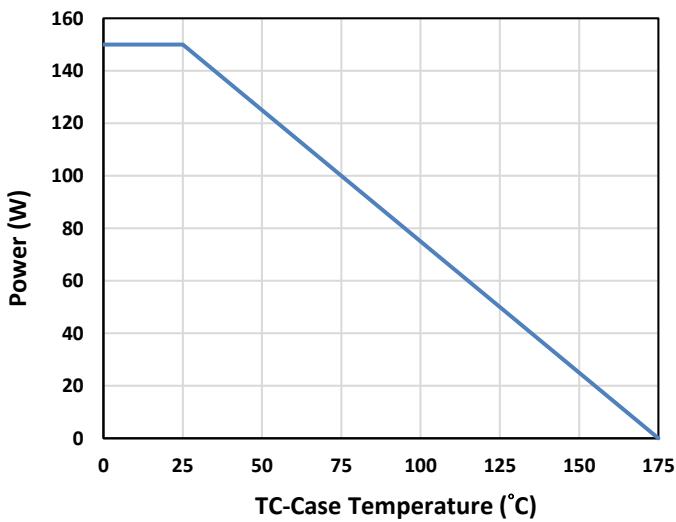


Fig 11. Power dissipation

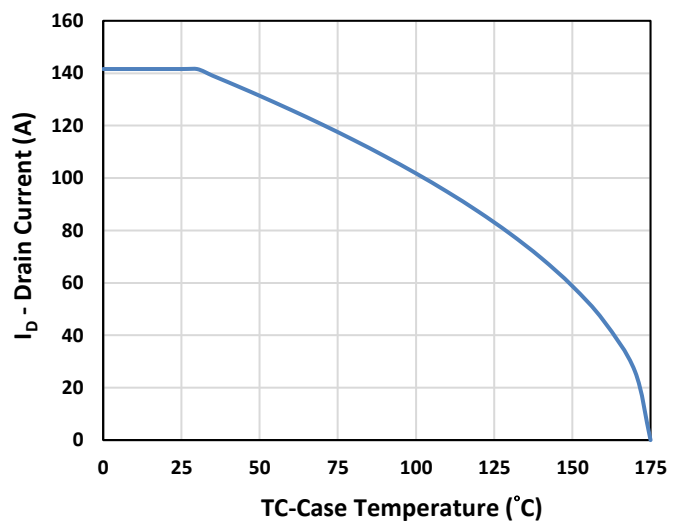


Fig 12. Drain current

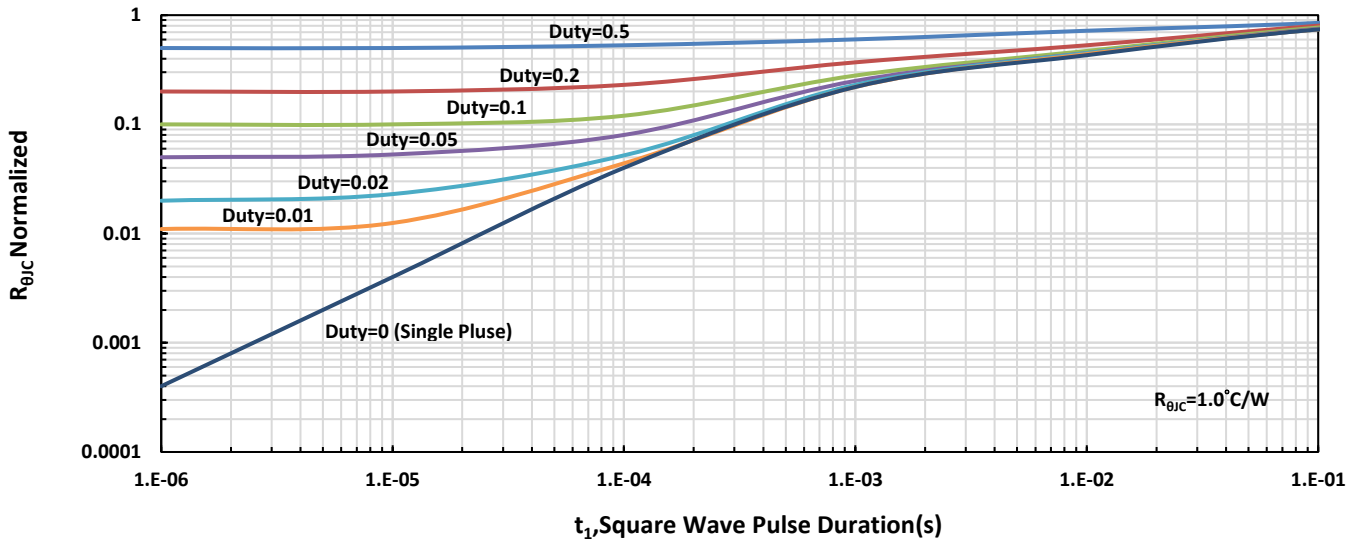


Fig 13. $R_{\theta JC}$ transient thermal impedance

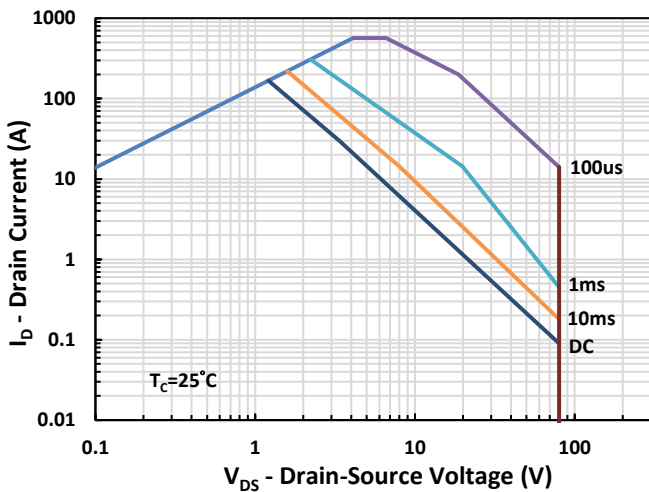


Fig 14. Safe operating area

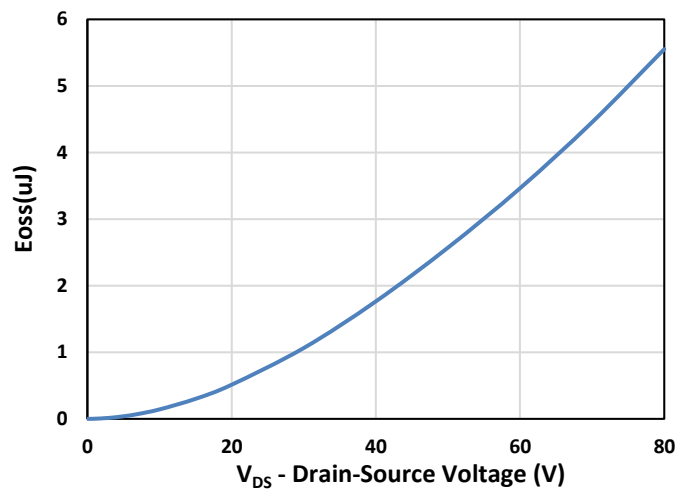


Fig.15 Typ. Coss stored energy

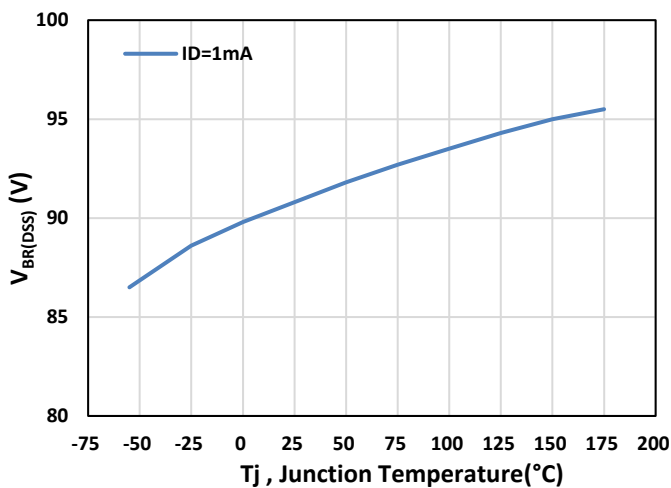


Fig.16 Drain-source breakdown voltage

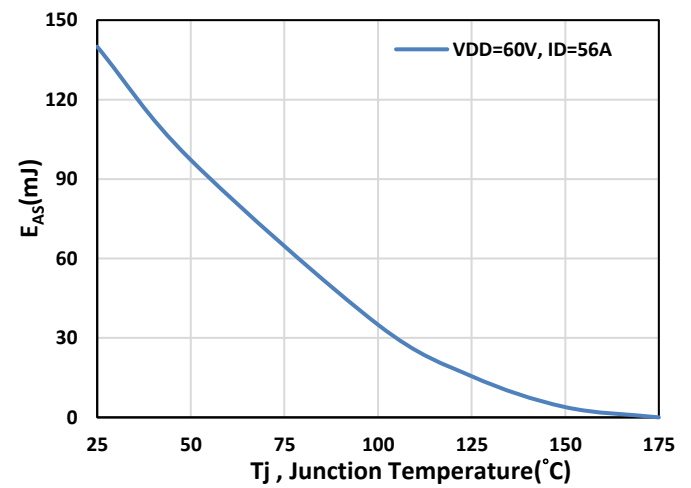


Fig.17: Avalanche energy

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▪ Marking Information:

